



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	Response Date *	Response Document ID				
NIC Components Corp.			2021-10-20					
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *	Duplicate Contact -> Authorized Representative				
Michael Mack	RoHS Coordinator	631-396-7500	mike.mack@niccomp.com					
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *	Supplier Comments or URL for Additional Information				
Michael Mack	Product Engineer & Product Co	631-396-7500	mike.mack@niccomp.com					
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
	NLTN16LS224AGCGTRF Trar		2004-10-01			1.184	g	Each
Alternate Recommendation				Alternate Item Comments				

## Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Matte Tin (Sn)	CU Alloy	Not Applicable	260 C	10 seconds	Not Applicable

Comments

Leaded Part - No MSL or reflow information

Save the fields in this form to a file

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Lock the fields on this form to prevent changes

Lock Supplier Fields

### RoHS Material Composition Declaration

Declaration Type \*

Detailed

<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium
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Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2002/95/EC and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.

<b>RoHS Declaration *</b>	3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any	<b>Supplier Acceptance *</b>	Accepted
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**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version	EL-2006/690/EC
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### Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	<b>Michael Mack</b>	Digitally signed by Michael Mack Date: 2019.09.10 09:01:43 -04'00'
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## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

+I	-I	Item/SubItem Name	+M	-M	Homogeneous Material	Weight	Unit of Measure	+C	-C	Level	Substance Category	+S	-S	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
		NLTN16LS224AGC			PCB_CCL	218.9168	mg			Supplier	Copper			Copper	7440-50-8		116.0259	mg			
					Supplier	Glass fiber				GLASS FABRIC	65997-17-3			87.56674	mg						
					Supplier	Epoxy Resin				Epoxy Resin	61788-97-4			15.32418	mg						
		PCB_Liquid photo			Supplier	Liquid				Formaldehyde, polymer	9003-36-5			4.218710	mg						
						Barium sulfate				7727-43-7				2.531262	mg						
						Carbon Black				1333-86-4				0.843742	mg						
						Silica				14464-46-1				0.421871	mg						
						Silicone				63148-62-9				0.126561	mg						
						Dibasic ester(DBE)				95481-62-2				0.084374	mg						
						2-Isopropylthioxanthone				5495-84-1				0.084374	mg						
						2-Methyl-4'-(methylthio)				71868-10-5				0.084374	mg						
						Melamine				108-78-1				0.025312	mg						
						Methoxypropoxypropan				34590-94-8				0.008437	mg						
						Solvent naphtha				64742-94-5				0.008437	mg						
		PCB_Thermal cu			Supplier	Metal				Poly[(o-cresyl glycidyl e	29690-82-2			0.091215	mg						
						Poly(bisphenol-A-co-ep				25068-38-6				0.091215	mg						
						Dibasic ester(DBE)				95481-62-2				0.045607	mg						
						Silica				14464-46-1				0.045607	mg						
						Titanium dioxide				13463-67-7				0.136823	mg						
						Dicyanodiamide				461-58-5				0.022803	mg						
						Silicone				63148-62-9				0.022803	mg						
		PCB_IMMERSION			Supplier	Metals				Nickel	7440-02-0			0.223477	mg						
						Gold				7440-57-5				0.004560	mg						

+M	-M	Common Mode C36.92304mg	+C	-C	Supplier	Oxide	+S	-S	Ferric oxide	1309-37-1	22.89228mg				
							+S	-S	Nickel Oxide	1313-99-1	4.061534mg				
							+S	-S	Zinc Oxide	1314-13-2	7.384608mg				
							+S	-S	Copper Oxide	1317-38-0	2.584612mg				
+M	-M	Common Mode C5.75424 mg	+C	-C	Supplier	Metal	+S	-S	Copper	7440-50-8	5.75424 mg				
+M	-M	Common Mode C1.43856 mg	+C	-C	Supplier	Resin	+S	-S	Polyurethane Resin	26680-22-8	1.43856 mg				
+M	-M	Common Mode C1.43856 mg	+C	-C	Supplier	Metal	+S	-S	Silver	7440-22-4	1.43856 mg				
+M	-M	Common Mode C0.47952 mg	+C	-C	Supplier	Metal	+S	-S	Nickel	7440-02-0	0.47952 mg				
+M	-M	Common Mode C0.47952 mg	+C	-C	Supplier	Metal	+S	-S	Tin	7440-31-5	0.47952 mg				
+M	-M	Common Mode C1.43856 mg	+C	-C	Supplier	Liquid	+S	-S	Epoxy resin	61788-97-4	0.71928 mg				
							+S	-S	Carbon black	1333-86-4	0.661737mg				
							+S	-S	Acrylated Aliphatic Ure	68987-79-1	0.057542mg				
+M	-M	SMD Pulse Trans\$398.8227mg	+C	-C	Supplier	Oxide	+S	-S	Ferric Oxide	1309-37-1	247.2700mg				
							+S	-S	Nickel Oxide	1313-99-1	43.87049mg				
							+S	-S	Zinc Oxide	1314-13-2	79.76454mg				
							+S	-S	Copper Oxide	1317-38-0	27.91758mg				
+M	-M	SMD Pulse Trans60.96652mg	+C	-C	Supplier	Metal	+S	-S	Copper	7440-50-8	60.96652mg				
+M	-M	SMD Pulse Trans15.24163mg	+C	-C	Supplier	Resin	+S	-S	Polyurethane Resin	26680-22-8	15.24163mg				
+M	-M	SMD Pulse Trans12.70136mg	+C	-C	Supplier	Metal	+S	-S	Silver	7440-22-4	12.70136mg				
+M	-M	SMD Pulse Trans2.540272mg	+C	-C	Supplier	Metal	+S	-S	Nickel	7440-02-0	2.540272mg				
+M	-M	SMD Pulse Trans2.540272mg	+C	-C	Supplier	Metal	+S	-S	Tin	7440-31-5	2.540272mg				
+M	-M	SMD Pulse Trans15.24163mg	+C	-C	Supplier	Metal	+S	-S	Ferric Oxide	1309-37-1	7.315983mg				
							+S	-S	Trimanganese tetraoxid	1317-35-7	1.828995mg				
							+S	-S	Zinc Oxide	1314-13-2	0.914497mg				
							+S	-S	Formaldehyde Polymer	9003-36-5	4.267656mg				
							+S	-S	Dicyanodiamide	461-58-5	0.457248mg				
							+S	-S	N-(2-methylphenyl)-N-(p	40027-50-7	0.304832mg				
							+S	-S	Carbon Black	1333-86-4	0.152416mg				
+M	-M	Iron shell_STEEL342.5905mg	+C	-C	Supplier	Metal	+S	-S	Stainless steel	12597-68-1	342.5905mg				
+M	-M	Iron shell_Nickel18.41108mg	+C	-C	Supplier	Metal	+S	-S	Nickel	7440-02-0	18.41108mg				
+M	-M	Solder Paste_Le 38.9536 mg	+C	-C	Supplier	Metal	+S	-S	Tin	7440-31-5	38.36929mg				
							+S	-S	Silver	7440-22-4	0.389536mg				

\* Required Field

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

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+S	-S	Copper	7440-50-8	0.194768	mg			
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